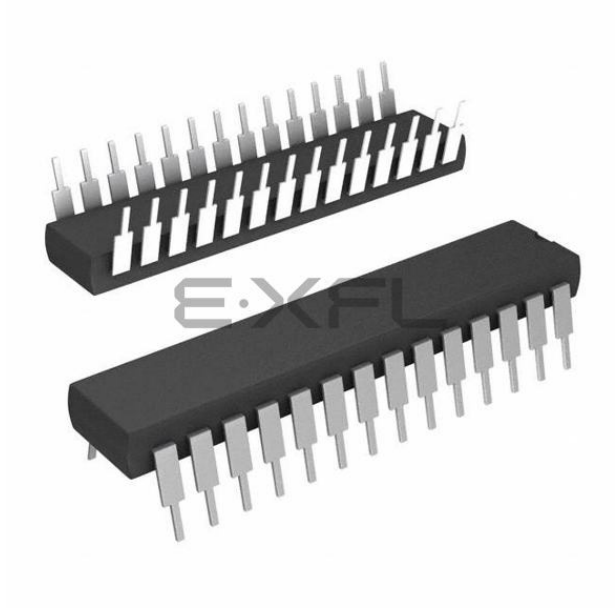

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Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 23x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1566-i-sp

TABLE 2: 28-PIN ALLOCATION TABLE (PIC16LF1566) (CONTINUED)

I/O	28-Pin SPDIP/SOIC/SSOP	28-Pin UQFN	Analog Channel	ADC and CVD	Timers	PWM	EUSART	MSSP	Interrupt	Pull-up	Basic
RC6	17	14	AN15	—	—	—	TX CK	—	—	—	—
RC7	18	15	AN26	—	—	—	RX DT	—	—	—	—
RE3	1	26	—	—	—	—	—	—	—	Y	$\overline{MCLR}$ V_{PP}
V_{DD}	20	17	—	—	—	—	—	—	—	—	V_{DD}
V_{SS}	8	5	—	—	—	—	—	—	—	—	V_{SS}
V_{SS}	19	16	—	—	—	—	—	—	—	—	V_{SS}

Note 1: Pin functions can be assigned to one of two pin locations via software.

TABLE 3: 40/44-PIN ALLOCATION TABLE (PIC16LF1567)

I/O	40-Pin PDIP	40-Pin UQFN	44-Pin TQFP	Analog Channel	ADC and CVD	Timers	PWM	EUSART	MSSP	Interrupt	Pull-Up	Basic
RA0	2	17	19	AN20	—	—	PWM10	—	SS1(1)	—	—	—
RA1	3	18	20	AN10	—	—	PWM11	—	SS2	—	—	—
RA2	4	19	21	AN0	VREF-	—	PWM12	—	—	—	—	—
RA3	5	20	22	AN1	VREF+		PWM13	—	—	—	—	—
RA4	6	21	23	AN2	—	T0CKI	—	—	—	—	—	—
RA5	7	22	24	AN21	—	—	—	—	SS1(1)	—	—	—
RA6	14	29	31	AN22	ADTRIG	—	—	—	—	—	—	CLKOUT
RA7	13	28	30	AN11	—	—	—	—	—	—	—	CLKIN
RB0	33	8	8	AN16	—	—	PWM20	—	—	INT IOC	Y	—
RB1	34	9	9	AN27	—	—	PWM21	—	—	IOC	Y	—
RB2	35	10	10	AN17	—	—	PWM22	—	—	IOC	Y	—
RB3	36	11	11	AN28	—	—	PWM23	—	—	IOC	Y	—
RB4	37	12	14	AN18	AD1GRDA(1) AD2GRDA(1)	—	—	—	—	IOC	Y	—
RB5	38	13	15	AN29	AD1GRDA(1) AD2GRDA(1)	T1G	—	—	—	IOC	Y	—
RB6	39	14	16	AN19	AD1GRDB(1) AD2GRDB(1)	—	—	—	—	IOC	Y	ICSPCLK ICDCLK
RB7	40	15	17	AN40	AD1GRDB(1) AD2GRDB(1)	—	—	—	—	IOC	Y	ICSPDAT ICDDAT
RC0	15	30	32	AN12	—	T1CKI	—	—	SDO2	—	—	—
RC1	16	31	35	AN23	—	—	PWM2	—	SCL2 SCK2	—	—	—
RC2	17	32	36	AN13	—	—	PWM1	—	SDA2 SDI2	—	—	—
RC3	18	33	37	AN24	—	—	—	—	SCL1 SCK1	—	—	—
RC4	23	38	42	AN14	—	—	—	—	SDA1 SDI1	—	—	—
RC5	24	39	43	AN25	—	—	—	—	SDO1 I2CLVL	—	—	—
RC6	25	40	44	AN15	—	—	—	TX CK	—	—	—	—
RC7	26	1	1	AN26	—	—	—	RX DT	—	—	—	—
RD0	19	34	38	AN42	—	—	—	—	—	—	—	—

Table of Contents

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TABLE 1-3: PIC16LF1567 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RC4/AN14/SDA1/SDI1	RC4	TTL	CMOS	General Purpose I/O.
	AN14	AN	—	ADC Channel Input for ADC1.
	SDA1	I^2C	OD	I^2C Data for MSSP1.
	SDI1	CMOS	—	SPI Data Input for MSSP1.
RC5/AN25/SDO1/I2CLVL	RC5	TTL	CMOS	General Purpose I/O.
	AN25	AN	—	ADC Channel Input for ADC2.
	SDO1	—	CMOS	SPI Data Output for MSSP1.
	I2CLVL	AN	—	I^2C Voltage Level Input.
RC6/AN15/TX/CK	RC6	TTL	CMOS	General Purpose I/O.
	AN15	AN	—	ADC Channel Input for ADC1.
	TX	—	CMOS	EUSART Asynchronous Transmit.
	CK	ST	CMOS	EUSART Synchronous Clock.
RC7/AN26/RX/DT	RC7	TTL	CMOS	General Purpose I/O.
	AN26	AN	—	ADC Channel Input for ADC2.
	RX	ST	—	EUSART Asynchronous Input.
	DT	ST	CMOS	EUSART Synchronous Data.
RD0/AN42	RD0	TTL	CMOS	General Purpose I/O.
	AN42	AN	—	ADC Channel Input for ADC2.
RD1/AN32	RD1	TTL	CMOS	General Purpose I/O.
	AN32	AN	—	ADC Channel Input for ADC1.
RD2/AN43	RD2	TTL	CMOS	General Purpose I/O.
	AN43	AN	—	ADC Channel Input for ADC2.
RD3/AN33	RD3	TTL	CMOS	General Purpose I/O.
	AN33	AN	—	ADC Channel Input for ADC1.
RD4/AN34	RD4	TTL	CMOS	General Purpose I/O.
	AN34	AN	—	ADC Channel Input for ADC1.
RD5/AN44	RD5	TTL	CMOS	General Purpose I/O.
	AN44	AN	—	ADC Channel Input for ADC2.
RD6/AN35	RD6	TTL	CMOS	General Purpose I/O.
	AN35	AN	—	ADC Channel Input for ADC1.
RD7/AN45	RD7	TTL	CMOS	General Purpose I/O.
	AN45	AN	—	ADC Channel Input for ADC2.
RE0/AN30	RE0	TTL	CMOS	General Purpose I/O.
	AN30	AN	—	ADC Channel Input for ADC1.
RE1/AN41	RE1	TTL	CMOS	General Purpose I/O.
	AN41	AN	—	ADC Channel Input for ADC2.
RE2/AN31	RE2	TTL	CMOS	General Purpose I/O.
	AN31	AN	—	ADC Channel Input for ADC1.
RE3/VPP/$\overline{MCLR}$	RE3	TTL	—	General Purpose Input with WPU.
	VPP	HV	—	Programming Voltage.
	$\overline{MCLR}$	ST	—	Master Clear with Internal Pull-up.

TABLE 3-11: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr.	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
Bank 6											
300h	INDF0(1)	Addressing this location uses contents of FSR0H/FSR0L to address data memory (not a physical register)								xxxx xxxx	uuuu uuuu
301h	INDF1(1)	Addressing this location uses contents of FSR1H/FSR1L to address data memory (not a physical register)								xxxx xxxx	uuuu uuuu
302h	PCL(1)	Program Counter (PC) Least Significant Byte								0000 0000	0000 0000
303h	STATUS(1)	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	---1 1000	---q quuu
304h	FSR0L(1)	Indirect Data Memory Address 0 Low Pointer								0000 0000	uuuu uuuu
305h	FSR0H(1)	Indirect Data Memory Address 0 High Pointer								0000 0000	0000 0000
306h	FSR1L(1)	Indirect Data Memory Address 1 Low Pointer								0000 0000	uuuu uuuu
307h	FSR1H(1)	Indirect Data Memory Address 1 High Pointer								0000 0000	0000 0000
308h	BSR(1)	—	—	—	BSR<4:0>					---0 0000	---0 0000
309h	WREG(1)	Working Register								0000 0000	uuuu uuuu
30Ah	PCLATH(1)	—	Write Buffer for the upper 7 bits of the Program Counter							-000 0000	-000 0000
30Bh	INTCON(1)	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	0000 0000	0000 0000
30Ch	—	Unimplemented								—	—
30Dh	—	Unimplemented								—	—
30Eh	—	Unimplemented								—	—
30Fh	—	Unimplemented								—	—
310h	—	Unimplemented								—	—
311h	—	Unimplemented								—	—
312h	—	Unimplemented								—	—
313h	—	Unimplemented								—	—
314h	—	Unimplemented								—	—
315h	—	Unimplemented								—	—
316h	—	Unimplemented								—	—
317h	—	Unimplemented								—	—
318h	—	Unimplemented								—	—
319h	—	Unimplemented								—	—
31Ah	—	Unimplemented								—	—
31Bh	—	Unimplemented								—	—
31Ch	—	Unimplemented								—	—
31Dh	—	Unimplemented								—	—
31Eh	—	Unimplemented								—	—
31Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations unimplemented, read as '0'.

Note 1: These registers can be accessed from any bank.
2: PIC16LF1567.
3: These registers/bits are available at two address locations, in Bank 1 and Bank 14.
4: PIC16LF1566 only.
5: Unimplemented, read as '1'.

6.4 Low-Power Brown-out Reset (LPBOR)

The Low-Power Brown-out Reset (LPBOR) operates like the BOR to detect low voltage conditions on the VDD pin. When too low of a voltage is detected, the device is held in Reset. When this occurs, a register bit (BOR) is changed to indicate that a BOR Reset has occurred. The $\overline{BOR}$ bit in PCON is used for both BOR and the LPBOR. Refer to Register 6-2.

The LPBOR voltage threshold (VLPBOR) has a wider tolerance than the BOR (VBOR), but requires much less current (LPBOR current) to operate. The LPBOR is intended for use when the BOR is configured as disabled (BOREN = 00) or disabled in Sleep mode (BOREN = 10).

Refer to Figure 6-1 to see how the LPBOR interacts with other modules.

6.4.1 ENABLING LPBOR

The LPBOR is controlled by the $\overline{LPBOR}$ bit of Configuration Words. When the device is erased, the LPBOR module defaults to disabled.

6.5 $\overline{MCLR}$

The $\overline{MCLR}$ is an optional external input that can reset the device. The $\overline{MCLR}$ function is controlled by the MCLRE bit of Configuration Words and the LVP bit of Configuration Words (Table 6-2).

TABLE 6-2: $\overline{MCLR}$ CONFIGURATION

MCLRE	LVP	$\overline{MCLR}$
0	0	Disabled
1	0	Enabled
x	1	Enabled

6.5.1 $\overline{MCLR}$ ENABLED

When $\overline{MCLR}$ is enabled and the pin is held low, the device is held in Reset. The $\overline{MCLR}$ pin is connected to VDD through an internal weak pull-up.

The device has a noise filter in the $\overline{MCLR}$ Reset path. The filter will detect and ignore small pulses.

Note:	A Reset does not drive the $\overline{MCLR}$ pin low.

6.5.2 $\overline{MCLR}$ DISABLED

When $\overline{MCLR}$ is disabled, the pin functions as a general purpose input and the internal weak pull-up is under software control. See **Section 11.3 "PORTA Registers"** for more information.

6.6 Watchdog Timer (WDT) Reset

The Watchdog Timer generates a Reset if the firmware does not issue a CLRWDT instruction within the time-out period. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register are changed to indicate the WDT Reset. See **Section 9.0 "Watchdog Timer (WDT)"** for more information.

6.7 RESET Instruction

A RESET instruction will cause a device Reset. The $\overline{RI}$ bit in the PCON register will be set to '0'. See Table 6-4 for default conditions after a RESET instruction has occurred.

6.8 Stack Overflow/Underflow Reset

The device can reset when the Stack Overflows or Underflows. The STKOVF or STKUNF bits of the PCON register indicate the Reset condition. These Resets are enabled by setting the STVREN bit in Configuration Words. See **Section 3.4.2 "Overflow/Underflow Reset"** for more information.

6.9 Programming Mode Exit

Upon exit of Programming mode, the device will behave as if a POR had just occurred.

6.10 Power-up Timer

The Power-up Timer optionally delays device execution after a BOR or POR event. This timer is typically used to allow VDD to stabilize before allowing the device to start running.

The Power-up Timer is controlled by the $\overline{PWRTE}$ bit of Configuration Words.

6.11 Start-up Sequence

Upon the release of a POR or BOR, the following must occur before the device will begin executing:

1. Power-up Timer runs to completion (if enabled).
2. $\overline{MCLR}$ must be released (if enabled).

The total time-out will vary based on oscillator configuration and Power-up Timer configuration. See **Section 5.0 "Oscillator Module"** for more information.

The Power-up Timer runs independently of $\overline{MCLR}$ Reset. If $\overline{MCLR}$ is kept low long enough, the Power-up Timer will expire. Upon bringing $\overline{MCLR}$ high, the device will begin execution after 10 FOSC cycles (see Figure 6-3). This is useful for testing purposes or to synchronize more than one device operating in parallel.

FIGURE 10-5: BLOCK WRITES TO FLASH PROGRAM MEMORY WITH 32 WRITE LATCHES

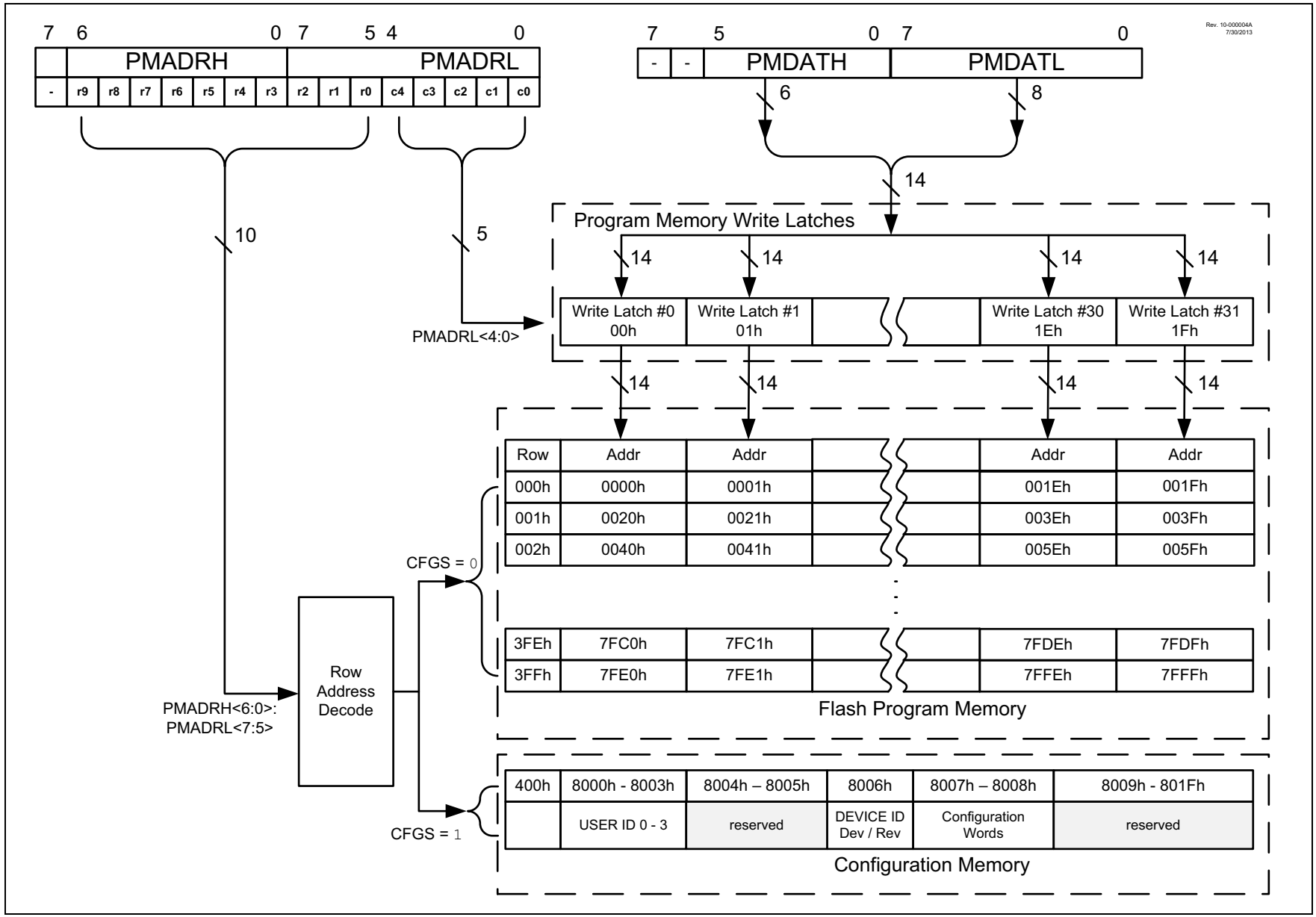
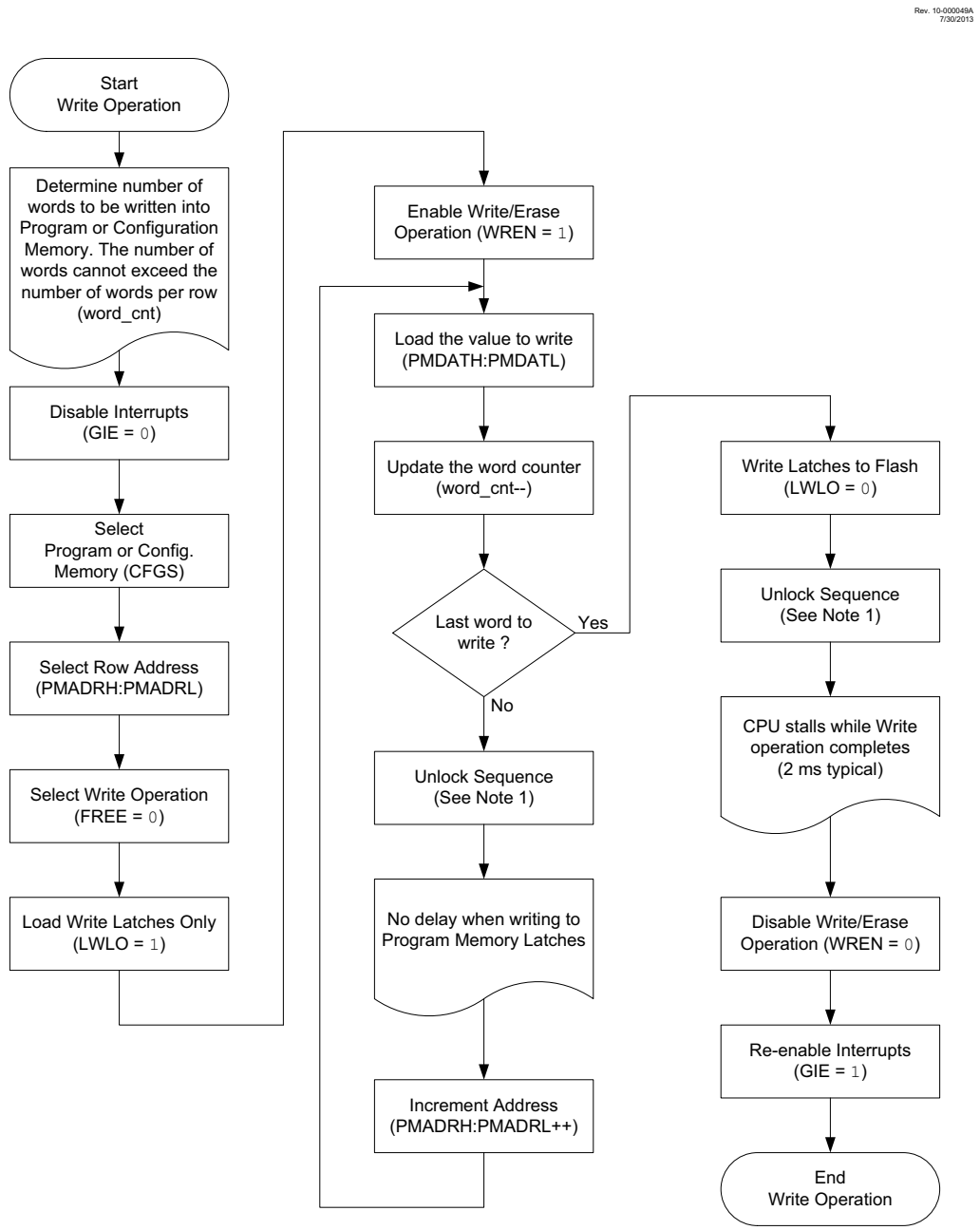


FIGURE 10-6: FLASH PROGRAM MEMORY WRITE FLOWCHART



Note 1: See Figure 10-3.

16.0 HARDWARE CAPACITIVE VOLTAGE DIVIDER (CVD) MODULE

The hardware Capacitive Voltage Divider (CVD) module is a peripheral, which allows the user to perform a relative capacitance measurement on any ADC channel using the internal ADC sample and hold capacitance as a reference. This relative capacitance measurement can be used to implement capacitive touch or proximity sensing applications.

The CVD operation begins with the ADC's internal sample and hold capacitor (C_{HOLD}) being disconnected from the path which connects it to the external capacitive sensor node. While disconnected, C_{HOLD} is precharged to V_{DD} or V_{SS}, while the path to the sensor node is also discharged to V_{DD} or V_{SS}. Typically, this node is discharged to the level opposite that of C_{HOLD}. When the precharge phase is complete, the V_{DD}/V_{SS} bias paths for the two nodes are shut off and C_{HOLD} and the path to the external sensor node are re-connected, at which time the acquisition phase of the CVD operation begins. During acquisition, a capacitive voltage divider is formed between the precharged C_{HOLD} the and sensor nodes, which results in a final voltage level settling on C_{HOLD}, which is determined by the capacitances and precharge levels of the two nodes involved. After acquisition, the ADC converts the voltage level held on C_{HOLD}. This process is then usually repeated with the selected precharge levels for both the C_{HOLD} and the inverted sensor nodes. Figure 16-1 shows the waveform for two inverted CVD measurements, which is also known is differential CVD measurement.

In a typical application, an Analog-to-Digital Converter (ADC) channel is attached to a pad on a Printed Circuit Board (PCB), which is electrically isolated from the end user. A capacitive change is detected on the ADC channel using the CVD conversion method when the end user places a finger over the PCB pad, the developer then can implement software to detect a touch or proximity event. Key features of this module include:

- Automated double sample conversions
- Two sets of result registers
- Inversion of second sample
- 7-bit precharge timer
- 7-bit acquisition timer
- Two guard ring output drives
- Adjustable sample and hold capacitor array
- Simultaneous CVD sampling on two ADCs

Note: For more information on capacitive voltage divider sensing method refer to the Application Note AN1478, *"mTouch® Sensing Solution Acquisition Methods Capacitive Voltage Divider"* (DS01478).

REGISTER 16-7: ADxCON2: ADC CONTROL REGISTER 2(1)

U-0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	U-0	U-0
—	TRIGSEL<2:0>			—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **TRIGSEL<2:0>:** Auto-Conversion Trigger Selection bits
- 111 = ADTRIG Falling Edge
- 110 = ADTRIG Rising Edge
- 101 = TMR2 match to PR2(1)
- 100 = Timer1 Overflow(1)
- 011 = Timer0 Overflow(1)
- 010 = TMR4 match to PR4
- 001 = Reserved
- 000 = No Auto Conversion Trigger selected

bit 3-0 **Unimplemented:** Read as '0'

Note 1: Signal also sets its corresponding interrupt flag.

17.1.3 SOFTWARE PROGRAMMABLE PRESCALER

A software programmable prescaler is available for exclusive use with Timer0. The prescaler is enabled by clearing the PSA bit of the OPTION_REG register.

Note:	The Watchdog Timer (WDT) uses its own independent prescaler.

There are eight prescaler options for the Timer0 module ranging from 1:2 to 1:256. The prescale values are selectable via the PS<2:0> bits of the OPTION_REG register. In order to have a 1:1 prescaler value for the Timer0 module, the prescaler must be disabled by setting the PSA bit of the OPTION_REG register.

The prescaler is not readable or writable. All instructions writing to the TMR0 register will clear the prescaler.

17.1.4 TIMER0 INTERRUPT

Timer0 will generate an interrupt when the TMR0 register overflows from FFh to 00h. The TMR0IF interrupt flag bit of the INTCON register is set every time the TMR0 register overflows, regardless of whether or not the Timer0 interrupt is enabled. The TMR0IF bit can only be cleared in software. The Timer0 interrupt enable is the TMR0IE bit of the INTCON register.

Note:	The Timer0 interrupt cannot wake the processor from Sleep since the timer is frozen during Sleep.

17.1.5 8-BIT COUNTER MODE SYNCHRONIZATION

When in 8-Bit Counter mode, the incrementing edge on the T0CKI pin must be synchronized to the instruction clock. Synchronization can be accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the instruction clock. The high and low periods of the external clocking source must meet the timing requirements as shown in **Section 25.0 "Electrical Specifications"**.

17.1.6 OPERATION DURING SLEEP

Timer0 cannot operate while the processor is in Sleep mode. The contents of the TMR0 register will remain unchanged while the processor is in Sleep mode.

20.2 SPI Mode Overview

The Serial Peripheral Interface (SPI) bus is a synchronous serial data communication bus that operates in Full-Duplex mode. Devices communicate in a master/slave environment where the master device initiates the communication. A slave device is controlled through a chip select known as Slave Select.

The SPI bus specifies four signal connections:

- Serial Clock (SCKx)
- Serial Data Out (SDOx)
- Serial Data In (SDIx)
- Slave Select ($\overline{SS}$x)

Figure 20-1 shows the block diagram of the MSSPx module when operating in SPI mode.

The SPI bus operates with a single master device and one or more slave devices. When multiple slave devices are used, an independent Slave Select connection is required from the master device to each slave device.

Figure 20-4 shows a typical connection between a master device and multiple slave devices.

The master selects only one slave at a time. Most slave devices have tri-state outputs so their output signal appears disconnected from the bus when they are not selected.

Transmissions involve two shift registers, eight bits in size, one in the master and one in the slave. With either the master or the slave device, data is always shifted out one bit at a time, with the Most Significant bit (MSb) shifted out first. At the same time, a new Least Significant bit (LSb) is shifted into the same register.

Figure 20-5 shows a typical connection between two processors configured as master and slave devices.

Data is shifted out of both shift registers on the programmed clock edge and latched on the opposite edge of the clock.

The master device transmits information out on its SDOx output pin which is connected to, and received by, the slave's SDIx input pin. The slave device transmits information out on its SDOx output pin, which is connected to, and received by, the master's SDIx input pin.

To begin communication, the master device first sends out the clock signal. Both the master and the slave devices should be configured for the same clock polarity.

The master device starts a transmission by sending out the MSb from its shift register. The slave device reads this bit from that same line and saves it into the LSb position of its shift register.

During each SPI clock cycle, a full-duplex data transmission occurs. This means that while the master device is sending out the MSb from its shift register (on its SDOx pin) and the slave device is reading this bit and saving it as the LSb of its shift register, that the slave device is also sending out the MSb from its shift register (on its SDOx pin) and the master device is reading this bit and saving it as the LSb of its shift register.

After eight bits have been shifted out, the master and slave have exchanged register values.

If there is more data to exchange, the shift registers are loaded with new data and the process repeats itself.

Whether the data is meaningful or not (dummy data), depends on the application software. This leads to three scenarios for data transmission:

- Master sends useful data and slave sends dummy data.
- Master sends useful data and slave sends useful data.
- Master sends dummy data and slave sends useful data.

Transmissions may involve any number of clock cycles. When there is no more data to be transmitted, the master stops sending the clock signal and it deselects the slave.

Every slave device connected to the bus that has not been selected through its slave select line must disregard the clock and transmission signals and must not transmit out any data of its own.

20.4 I²C MODE OPERATION

All MSSPx I²C communication is byte oriented and shifted out MSb first. Six SFR registers and two interrupt flags interface the module with the PIC® microcontroller and user software. Two pins, SDAx and SCLx, are exercised by the module to communicate with other external I²C devices.

20.4.1 BYTE FORMAT

All communication in I²C is done in 9-bit segments. A byte is sent from a master to a slave or vice-versa, followed by an Acknowledge bit sent back. After the eighth falling edge of the SCLx line, the device outputting data on the SDAx changes that pin to an input and reads in an acknowledge value on the next clock pulse.

The clock signal, SCLx, is provided by the master. Data is valid to change while the SCLx signal is low, and sampled on the rising edge of the clock. Changes on the SDAx line while the SCLx line is high define special conditions on the bus, explained below.

20.4.2 DEFINITION OF I²C TERMINOLOGY

There is language and terminology in the description of I²C communication that have definitions specific to I²C. That word usage is defined below and may be used in the rest of this document without explanation. This table was adapted from the Philips I²C specification.

20.4.3 SDAX AND SCLX PINS

Selection of any I²C mode with the SSPEN bit set, forces the SCLx and SDAx pins to be open-drain. These pins should be set by the user to inputs by setting the appropriate TRIS bits.

Note: Data is tied to output zero when an I²C mode is enabled.

20.4.4 SDAX HOLD TIME

The hold time of the SDAx pin is selected by the SDAHT bit of the SSPxCON3 register. Hold time is the time SDAx is held valid after the falling edge of SCLx. Setting the SDAHT bit selects a longer 300 ns minimum hold time and may help on buses with large capacitance.

TABLE 20-2: I²C BUS TERMS

TERM	Description
Transmitter	The device which shifts data out onto the bus.
Receiver	The device which shifts data in from the bus.
Master	The device that initiates a transfer, generates clock signals and terminates a transfer.
Slave	The device addressed by the master.
Multi-master	A bus with more than one device that can initiate data transfers.
Arbitration	Procedure to ensure that only one master at a time controls the bus. Winning arbitration ensures that the message is not corrupted.
Synchronization	Procedure to synchronize the clocks of two or more devices on the bus.
Idle	No master is controlling the bus, and both SDAx and SCLx lines are high.
Active	Any time one or more master devices are controlling the bus.
Addressed Slave	Slave device that has received a matching address and is actively being clocked by a master.
Matching Address	Address byte that is clocked into a slave that matches the value stored in SSPxADD.
Write Request	Slave receives a matching address with R/$\overline{W}$ bit clear, and is ready to clock in data.
Read Request	Master sends an address byte with the R/$\overline{W}$ bit set, indicating that it wishes to clock data out of the Slave. This data is the next and all following bytes until a Restart or Stop.
Clock Stretching	When a device on the bus hold SCLx low to stall communication.
Bus Collision	Any time the SDAx line is sampled low by the module while it is outputting and expected high state.

20.5.3.3 7-bit Transmission with Address Hold Enabled

Setting the AHEN bit of the SSPxCON3 register enables additional clock stretching and interrupt generation after the eighth falling edge of a received matching address. Once a matching address has been clocked in, CKP is cleared and the SSPxIF interrupt is set.

Figure 20-19 displays a standard waveform of a 7-bit Address Slave Transmission with AHEN enabled.

1. Bus starts Idle.
2. Master sends Start condition; the S bit of SSPxSTAT is set; SSPxIF is set if interrupt on Start detect is enabled.
3. Master sends matching address with R/$\overline{W}$ bit set. After the eighth falling edge of the SCLx line the CKP bit is cleared and SSPxIF interrupt is generated.
4. Slave software clears SSPxIF.
5. Slave software reads the ACKTIM bit of SSPxCON3 register, and R/$\overline{W}$ and D/$\overline{A}$ of the SSPxSTAT register to determine the source of the interrupt.
6. Slave reads the address value from the SSPxBUF register clearing the BF bit.
7. Slave software decides from this information if it wishes to $\overline{ACK}$ or not $\overline{ACK}$ and sets the ACKDT bit of the SSPxCON2 register accordingly.
8. Slave sets the CKP bit releasing SCLx.
9. Master clocks in the $\overline{ACK}$ value from the slave.
10. Slave hardware automatically clears the CKP bit and sets SSPxIF after the $\overline{ACK}$ if the R/$\overline{W}$ bit is set.
11. Slave software clears SSPxIF.
12. Slave loads value to transmit to the master into SSPxBUF setting the BF bit.

Note: SSPxBUF cannot be loaded until after the $\overline{ACK}$.

13. Slave sets CKP bit releasing the clock.
14. Master clocks out the data from the slave and sends an $\overline{ACK}$ value on the ninth SCLx pulse.
15. Slave hardware copies the $\overline{ACK}$ value into the ACKSTAT bit of the SSPxCON2 register.
16. Steps 10-15 are repeated for each byte transmitted to the master from the slave.
17. If the master sends a not $\overline{ACK}$ the slave releases the bus allowing the master to send a Stop and end the communication.

Note: Master must send a not $\overline{ACK}$ on the last byte to ensure that the slave releases the SCLx line to receive a Stop.

21.1.2 EUSART ASYNCHRONOUS RECEIVER

The Asynchronous mode is typically used in RS-232 systems. The receiver block diagram is shown in Figure 21-2. The data is received on the RX/DT pin and drives the data recovery block. The data recovery block is actually a high-speed shifter operating at 16 times the baud rate, whereas the serial Receive Shift Register (RSR) operates at the bit rate. When all eight or nine bits of the character have been shifted in, they are immediately transferred to a two character First-In-First-Out (FIFO) memory. The FIFO buffering allows reception of two complete characters and the start of a third character before software must start servicing the EUSART receiver. The FIFO and RSR registers are not directly accessible by software. Access to the received data is via the RCREG register.

21.1.2.1 Enabling the Receiver

The EUSART receiver is enabled for asynchronous operation by configuring the following three control bits:

- CREN = 1
- SYNC = 0
- SPEN = 1

All other EUSART control bits are assumed to be in their default state.

Setting the CREN bit of the RCSTA register enables the receiver circuitry of the EUSART. Clearing the SYNC bit of the TXSTA register configures the EUSART for asynchronous operation. Setting the SPEN bit of the RCSTA register enables the EUSART. The programmer must set the corresponding TRISx bit to configure the RX/DT I/O pin as an input.

Note:	If the RX/DT function is on an analog pin, the corresponding ANSELx bit must be cleared for the receiver to function.

21.1.2.2 Receiving Data

The receiver data recovery circuit initiates character reception on the falling edge of the first bit. The first bit, also known as the Start bit, is always a zero. The data recovery circuit counts one-half bit time to the center of the Start bit and verifies that the bit is still a zero. If it is not a zero then the data recovery circuit aborts character reception, without generating an error, and resumes looking for the falling edge of the Start bit. If the Start bit zero verification succeeds then the data recovery circuit counts a full bit time to the center of the next bit. The bit is then sampled by a majority detect circuit and the resulting '0' or '1' is shifted into the RSR. This repeats until all data bits have been sampled and shifted into the RSR. One final bit time is measured and the level sampled. This is the Stop bit, which is always a '1'. If the data recovery circuit samples a '0' in the Stop bit position then a framing error is set for this character, otherwise the framing error is cleared for this character. See **Section 21.1.2.4 "Receive Framing Error"** for more information on framing errors.

Immediately after all data bits and the Stop bit have been received, the character in the RSR is transferred to the EUSART receive FIFO and the RCIF interrupt flag bit of the PIR1 register is set. The top character in the FIFO is transferred out of the FIFO by reading the RCREG register.

Note:	If the receive FIFO is overrun, no additional characters will be received until the overrun condition is cleared. See **Section 21.1.2.5 "Receive Overrun Error"** for more information on overrun errors.

21.1.2.3 Receive Interrupts

The RCIF interrupt flag bit of the PIR1 register is set whenever the EUSART receiver is enabled and there is an unread character in the receive FIFO. The RCIF interrupt flag bit is read-only, it cannot be set or cleared by software.

RCIF interrupts are enabled by setting all of the following bits:

- RCIE, Interrupt Enable bit of the PIE1 register
- PEIE, Peripheral Interrupt Enable bit of the INTCON register
- GIE, Global Interrupt Enable bit of the INTCON register

The RCIF interrupt flag bit will be set when there is an unread character in the FIFO, regardless of the state of interrupt enable bits.

TABLE 21-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 32.000 MHz			FOSC = 20.000 MHz			FOSC = 18.432 MHz			FOSC = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	26666	300.0	0.00	16665	300.0	0.00	15359	300.0	0.00	9215
1200	1200	0.00	6666	1200	-0.01	4166	1200	0.00	3839	1200	0.00	2303
2400	2400	0.01	3332	2400	0.02	2082	2400	0.00	1919	2400	0.00	1151
9600	9604	0.04	832	9597	-0.03	520	9600	0.00	479	9600	0.00	287
10417	10417	0.00	767	10417	0.00	479	10425	0.08	441	10433	0.16	264
19.2k	19.18k	-0.08	416	19.23k	0.16	259	19.20k	0.00	239	19.20k	0.00	143
57.6k	57.55k	-0.08	138	57.47k	-0.22	86	57.60k	0.00	79	57.60k	0.00	47
115.2k	115.9k	0.64	68	116.3k	0.94	42	115.2k	0.00	39	115.2k	0.00	23

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 8.000 MHz			FOSC = 4.000 MHz			FOSC = 3.6864 MHz			FOSC = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	6666	300.0	0.01	3332	300.0	0.00	3071	300.1	0.04	832
1200	1200	-0.02	1666	1200	0.04	832	1200	0.00	767	1202	0.16	207
2400	2401	0.04	832	2398	0.08	416	2400	0.00	383	2404	0.16	103
9600	9615	0.16	207	9615	0.16	103	9600	0.00	95	9615	0.16	25
10417	10417	0	191	10417	0.00	95	10473	0.53	87	10417	0.00	23
19.2k	19.23k	0.16	103	19.23k	0.16	51	19.20k	0.00	47	19.23k	0.16	12
57.6k	57.14k	-0.79	34	58.82k	2.12	16	57.60k	0.00	15	—	—	—
115.2k	117.6k	2.12	16	111.1k	-3.55	8	115.2k	0.00	7	—	—	—

FIGURE 25-5: CLKOUT AND I/O TIMING

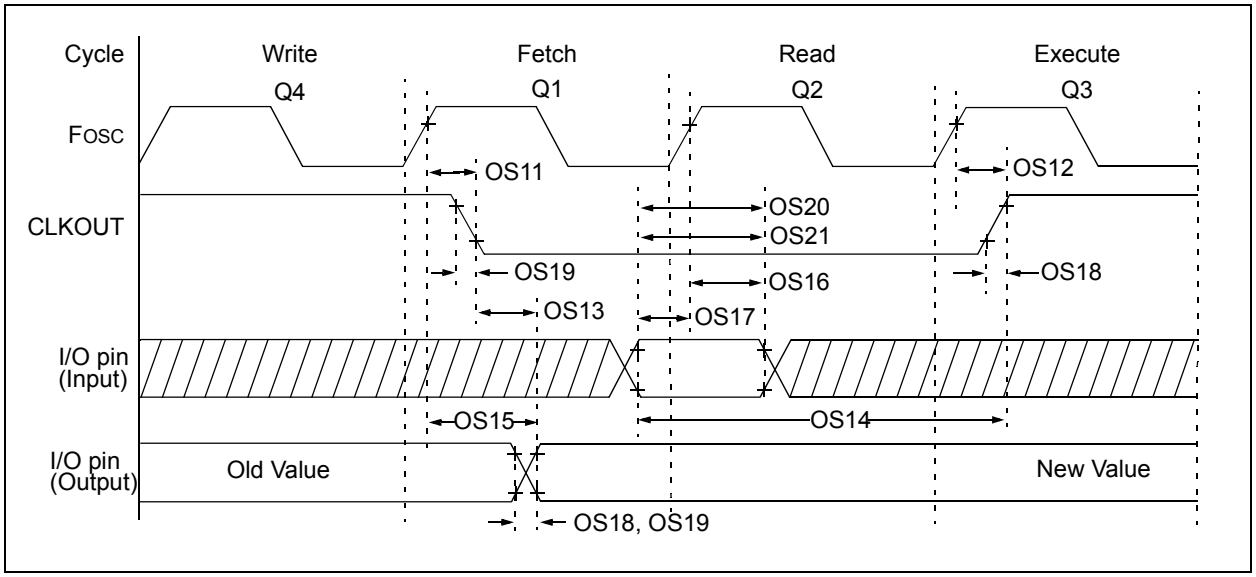


TABLE 25-9: CLKOUT AND I/O TIMING PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ.†**	**Max.**	**Units**	**Conditions**
OS11	TosH2ckL	FOSC↑ to CLKOUT↓ (1)	—	—	70	ns	VDD = 3.3-3.6V
OS12	TosH2ckH	FOSC↑ to CLKOUT↑ (1)	—	—	72	ns	VDD = 3.3-3.6V
OS13	TckL2ioV	CLKOUT↓ to Port out valid(1)	—	—	20	ns	
OS14	TioV2ckH	Port input valid before CLKOUT↑(1)	TOSC + 200 ns	—	—	ns	
OS15	TosH2ioV	Fosc↑ (Q1 cycle) to Port out valid	—	50	70*	ns	VDD = 3.3-3.6V
OS16	TosH2ioI	Fosc↑ (Q2 cycle) to Port input invalid (I/O in hold time)	50	—	—	ns	VDD = 3.3-3.6V
OS17	TioV2osH	Port input valid to Fosc↑ (Q2 cycle) (I/O in setup time)	20	—	—	ns	
OS18*	TioR	Port output rise time	—	15	32	ns	VDD = 2.0V
OS19*	TioF	Port output fall time	—	28	55	ns	VDD = 2.0V
OS20*	Tinp	INT pin input high or low time	25	—	—	ns	
OS21*	Tioc	Interrupt-on-Change new input level time	25	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ." column is at 3.0V, 25°C unless otherwise stated.

Note 1: Measurements are taken in EC mode where CLKOUT output is 4 x TOSC.

27.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

27.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

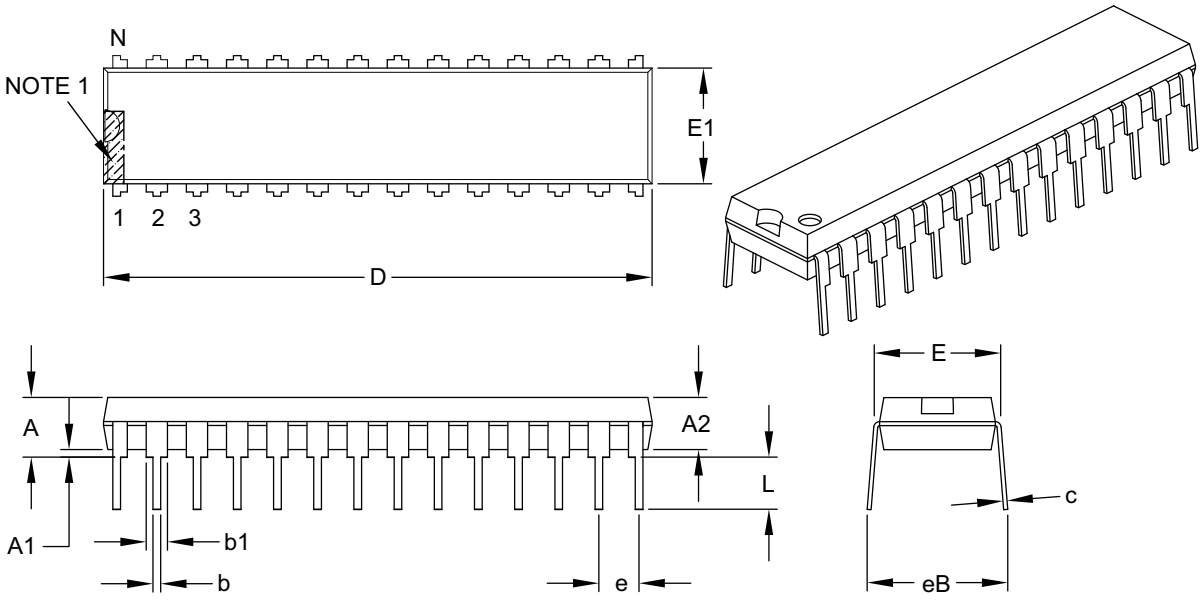
- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

28.2 Package Details

The following sections give the technical details of the packages.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

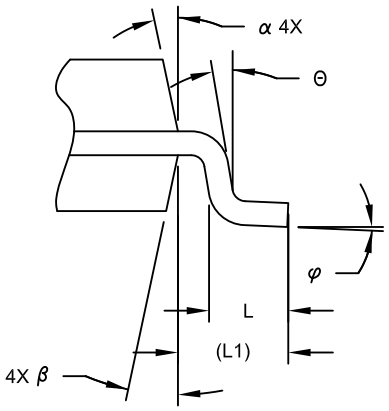
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

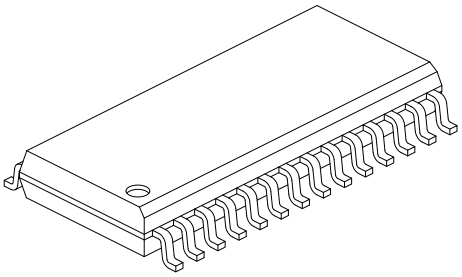
Microchip Technology Drawing C04-070B

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

